MOTOROLA

MC1699

BEING DISCONTINUED
(LIFETIME BUY UNTIL JUNE 14, 1989)

DIVIDE-BY-FOUR GIGAHERTZ COUNTER

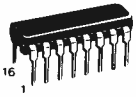
The MC1699 is a divide-by-four gigahertz counter. The clock input requires an ac coupled driving signal of 800 mV amplitude (typical). The clock toggles two divide-by-two stages, and the complementary outputs (50% duty cycle) are taken from the second stage.

The MC1699 includes clock enable and reset. The reset is compatible with MECL III voltage levels. The enable input requires a V_{IL} of −2.0 V max. Reset operates only when either the clock or the enable is high.

Pin 11 (13) is available for connection of a decoupling capacitor to ground. This capacitor stabilizes the reference point which is internally coupled to the clock input.

DIVIDE-BY-FOUR GIGAHERTZ COUNTER

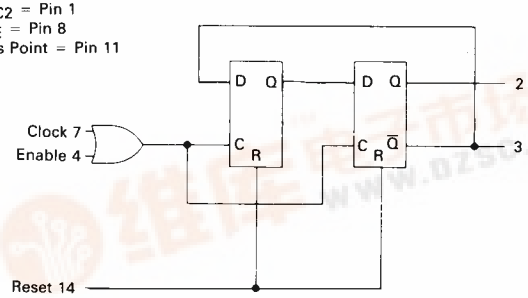
L SUFFIX
CERAMIC PACKAGE
CASE 620



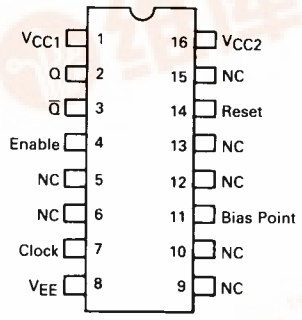
P SUFFIX
PLASTIC PACKAGE
CASE 648

LOGIC DIAGRAM

V_{CC1} = Pin 16
V_{CC2} = Pin 1
V_{EE} = Pin 8
Bias Point = Pin 11



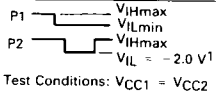
PIN ASSIGNMENT



ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	−30°C Min	−30°C Max	+25°C Min	+25°C Max	+85°C Min	+85°C Max	Unit	Conditions
Power Supply Drain Current	I_E	—	—	—	57	—	—	mAdc	All inputs and outputs open except Clock = $V_{IHC} \cong -4.0$ Vdc
Input Current Reset Enable	I_{inH}	 — —	 — —	 — —	 500 265	 — —	 — —	μAdc	V_{IHmax} to Reset, V_{IL} to Enable, V_{EE} to Clock. V_{ILmin} to Reset, V_{IHmax} to Enable, V_{EE} to Clock.
Logic "1" Output Voltage	V_{OH}	−1.085	−0.875	−1.0	−0.81	−0.93	−0.7	Vdc	See Note 2. Or, apply P1 to Reset and V_{IHmax} to Enable (See Test Conditions below).
Logic "0" Output Voltage	V_{OL}	—	−1.63	—	−1.6	—	−1.555	Vdc	
Toggle Frequency (high frequency operation)	f_{Tog}	1.0	—	1.0	—	1.0	—	GHz	V_{IL}[1] to Enable. See Test Circuit and Application Information.
Toggle Frequency (low frequency sine wave input)	f_{Tog}	—	—	—	100	—	—	MHz	

1. Enable input requires $V_{IL} \cong -2.0$ V max.
2. Reset counter by applying pulse P1 to pin 14, then toggle outputs by applying pulse P2 to pin 4 for 2 cycles. Hold power during pulse sequence. Hold clock input @ V_{EE}.



Test Conditions: $V_{CC1} = V_{CC2} = 0$, $V_{EE} = 7.0$ Vdc

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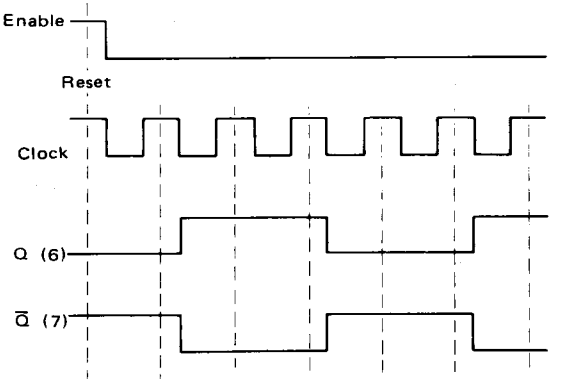
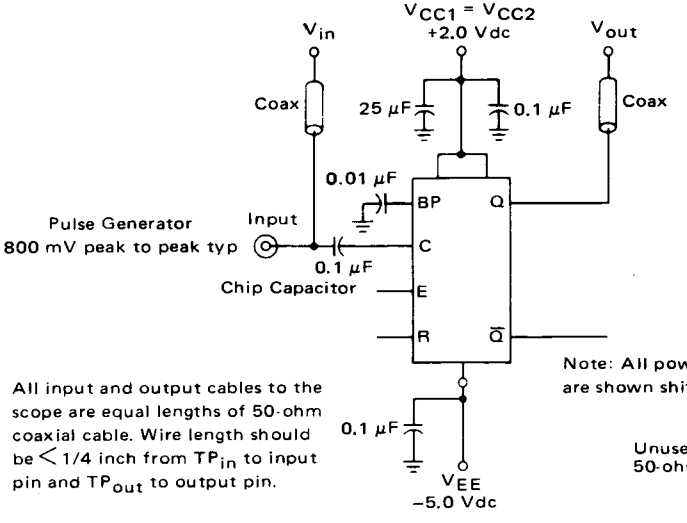
TIMING DIAGRAM



TOGGLE FREQUENCY TEST CIRCUIT



All input and output cables to the scope are equal lengths of 50-ohm coaxial cable. Wire length should be < 1/4 inch from TP_{in} to input pin and TP_{out} to output pin.

Note: All power supply and logic levels are shown shifted 2 volts positive.

Unused outputs connected to a 50-ohm resistor to ground.

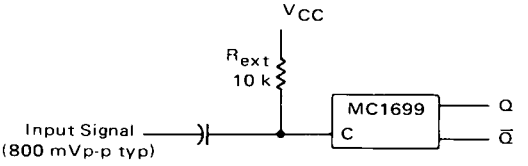
APPLICATION INFORMATION

The MC1699 is a very high speed divide-by-four counter intended for prescaler applications. The reset provides increased flexibility for counter and time measuring requirements.

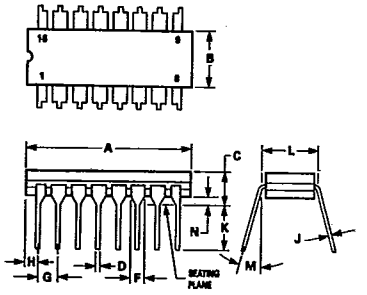
The clock input is designed to accept a capacitor-coupled sine wave signal for frequencies above 100 MHz. Below 100 MHz waveshaping is recommended to obtain good MECL III or MECL 10,000 edge speeds.

With a continuous input signal the clock can be capacitor-coupled with no problems. However, if the clock is interrupted and the clock input floats to the bias point reference voltage, the counter may oscillate. To prevent this oscillation, an external resistor can be added as shown in Figure 1. This resistor is recommended only when the clock is interrupted and serves no useful function with a continuous signal. Also, this external resistor is not required when the enable input is used to gate the clock signal.

FIGURE 1



L SUFFIX
CERAMIC PACKAGE
CASE 620-09

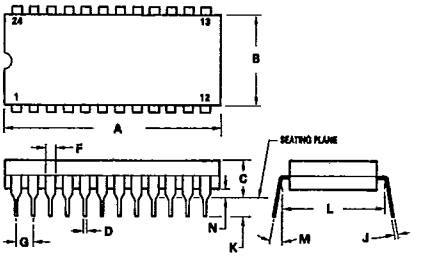


DIM	MILLIMETERS MIN	MILLIMETERS MAX	INCHES MIN	INCHES MAX
A	19.05	19.81	0.750	0.780
B	6.22	6.98	0.245	0.275
C	4.06	5.08	0.160	0.200
D	0.38	0.51	0.015	0.020
F	1.40	1.65	0.055	0.065
G	2.54 BSC		0.100 BSC	
H	0.51	1.14	0.020	0.045
J	0.20	0.30	0.008	0.012
K	3.18	4.06	0.125	0.160
L	7.37	7.87	0.290	0.310
M	—	15°	—	15°
N	0.51	1.02	0.020	0.040

NOTES:
1. LEADS WITHIN 0.13 mm (0.005) RADIUS OF TRUE POSITION AT SEATING PLANE AT MAXIMUM MATERIAL CONDITION.
2. PACKAGE INDEX: NOTCH IN LEAD NOTCH IN CERAMIC OR INK DOT.
3. DIM "L" TO CENTER OF LEADS WHEN FORMED PARALLEL.

L SUFFIX
CERAMIC PACKAGE
CASE 623-05

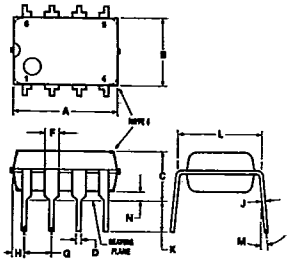
(LW SUFFIX FOR MC10H181 ONLY)



DIM	MILLIMETERS MIN	MILLIMETERS MAX	INCHES MIN	INCHES MAX
A	31.24	32.77	1.230	1.290
B	12.70	15.49	0.500	0.610
C	4.06	5.59	0.160	0.220
D	0.41	0.51	0.016	0.020
F	1.27	1.52	0.050	0.060
G	2.54 BSC		0.100 BSC	
J	0.20	0.30	0.008	0.012
K	3.18	4.06	0.125	0.160
L	15.24 BSC		0.600 BSC	
M	0°	15°	0°	15°
N	0.51	1.27	0.020	0.050

NOTES:
1. DIM "L" TO CENTER OF LEADS WHEN FORMED PARALLEL.
2. LEADS WITHIN 0.13 mm (0.005) RADIUS OF TRUE POSITION AT SEATING PLANE AT MAXIMUM MATERIAL CONDITION. (WHEN FORMED PARALLEL).

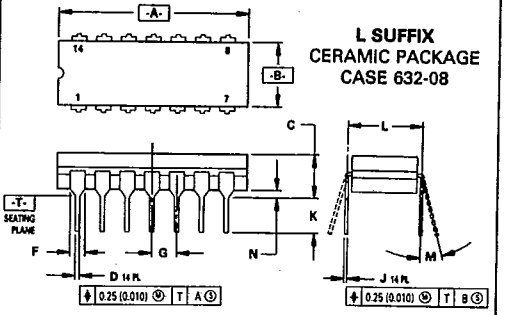
P SUFFIX
PLASTIC PACKAGE
CASE 626-04



DIM	MILLIMETERS MIN	MILLIMETERS MAX	INCHES MIN	INCHES MAX
A	9.40	10.16	0.370	0.400
B	6.10	6.60	0.240	0.260
C	3.94	4.45	0.155	0.175
D	0.38	0.51	0.015	0.020
F	1.02	1.52	0.040	0.060
G	2.54 BSC		0.100 BSC	
H	0.76	1.27	0.030	0.050
J	0.20	0.30	0.008	0.012
K	2.92	3.43	0.115	0.135
L	7.62 BSC		0.300 BSC	
M	—	10°	—	10°
N	0.51	0.76	0.020	0.030

NOTES:
1. LEAD POSITIONAL TOLERANCE: ⌖ ⌀ 0.13 (0.005) Ⓜ T A Ⓢ B Ⓢ
2. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
3. PACKAGE CONTOUR OPTIONAL (ROUND OR SQUARE CORNERS).
4. DIMENSIONS A AND B ARE DATUMS.
5. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

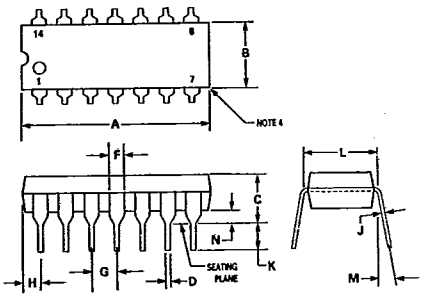
L SUFFIX
CERAMIC PACKAGE
CASE 632-08



DIM	MILLIMETERS MIN	MILLIMETERS MAX	INCHES MIN	INCHES MAX
A	19.05	19.94	0.750	0.785
B	6.73	7.11	0.245	0.280
C	3.94	5.08	0.155	0.200
D	0.39	0.50	0.015	0.020
F	1.40	1.65	0.055	0.065
G	2.54 BSC		0.100 BSC	
J	0.21	0.38	0.008	0.015
K	3.18	4.31	0.125	0.173
L	7.62 BSC		0.300 BSC	
M	0°	15°	0°	15°
N	0.51	1.01	0.020	0.040

NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
4. DIM F MAY NARROW TO 0.76 (0.030) WHERE THE LEAD ENTERS THE CERAMIC BODY.

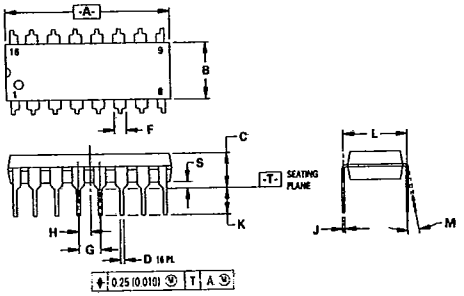
P SUFFIX
PLASTIC PACKAGE
CASE 646-06



DIM	MILLIMETERS MIN	MILLIMETERS MAX	INCHES MIN	INCHES MAX
A	18.16	19.56	0.715	0.770
B	6.10	6.60	0.240	0.260
C	3.69	4.69	0.145	0.185
D	0.38	0.53	0.015	0.021
F	1.02	1.78	0.040	0.070
G	2.54 BSC		0.100 BSC	
H	1.32	2.41	0.052	0.095
J	0.20	0.38	0.008	0.015
K	2.92	3.43	0.115	0.135
L	7.62 BSC		0.300 BSC	
M	0°	10°	0°	10°
N	0.39	1.01	0.015	0.039

NOTES:
1. LEADS WITHIN 0.13 mm (0.005) RADIUS OF TRUE POSITION AT SEATING PLANE AT MAXIMUM MATERIAL CONDITION.
2. DIMENSION "L" TO CENTER OF LEADS WHEN FORMED PARALLEL.
3. DIMENSION "B" DOES NOT INCLUDE MOLD FLASH.
4. ROUNDED CORNERS OPTIONAL.

P SUFFIX
PLASTIC PACKAGE
CASE 648-08

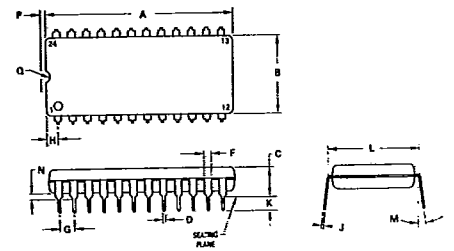


DIM	MILLIMETERS MIN	MILLIMETERS MAX	INCHES MIN	INCHES MAX
A	18.80	19.55	0.740	0.770
B	6.35	6.85	0.250	0.270
C	3.69	4.44	0.145	0.175
D	0.39	0.53	0.015	0.021
F	1.02	1.77	0.040	0.070
G	2.54 BSC		0.100 BSC	
H	1.27 BSC		0.050 BSC	
J	0.21	0.38	0.008	0.015
K	2.80	3.30	0.110	0.130
L	7.50	7.74	0.295	0.305
M	0°	10°	0°	10°
S	0.51	1.01	0.020	0.040

NOTES.
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION "L" TO CENTER OF LEADS WHEN FORMED PARALLEL.
4. DIMENSION "B" DOES NOT INCLUDE MOLD FLASH.
5. ROUNDED CORNERS OPTIONAL.

P SUFFIX
PLASTIC PACKAGE
CASE 649-03

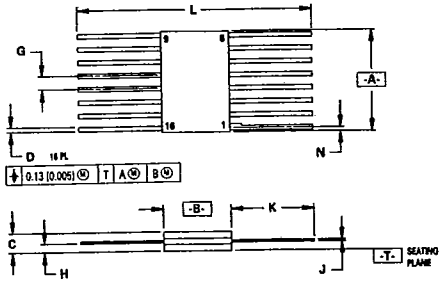
(PW SUFFIX FOR MC10H181 ONLY)



DIM	MILLIMETERS MIN	MILLIMETERS MAX	INCHES MIN	INCHES MAX
A	31.50	32.13	1.240	1.265
B	13.21	13.72	0.520	0.540
C	4.70	5.21	0.185	0.205
D	0.38	0.51	0.015	0.020
F	1.02	1.52	0.040	0.060
G	2.54 BSC		0.100 BSC	
H	1.65	2.16	0.065	0.085
J	0.20	0.30	0.008	0.012
K	2.92	3.43	0.115	0.135
L	14.99	15.49	0.590	0.610
M	—	10°	—	10°
N	0.51	1.02	0.020	0.040
P	0.13	0.38	0.005	0.015
Q	0.51	0.76	0.020	0.030

NOTES:
1. LEADS WITHIN 0.13 mm (0.005) RADIUS OF TRUE POSITION AT SEATING PLANE AT MAXIMUM MATERIAL CONDITION
2. DIMENSION "L" TO CENTER OF LEADS WHEN FORMED PARALLEL

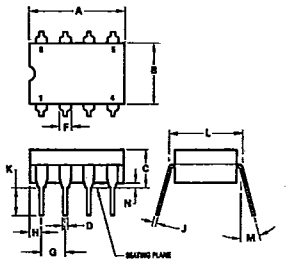
F SUFFIX
CERAMIC PACKAGE
CASE 650-05



DIM	MILLIMETERS MIN	MILLIMETERS MAX	INCHES MIN	INCHES MAX
A	9.40	9.90	0.370	0.390
B	6.23	6.60	0.245	0.260
C	1.53	2.15	0.060	0.085
D	0.36	0.48	0.014	0.019
G	1.27 BSC		0.050 BSC	
H	0.64	0.01	0.025	0.040
J	0.11	0.17	0.004	0.007
K	6.35	9.39	0.250	0.370
L	18.93	—	0.745	—
N	—	0.50	—	0.020

NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION "A" AND "B" ALLOW FOR LID MISALIGNMENT, AND GLASS MENISCUS.
4. DIMENSION "H" SHALL BE MEASURED AT THE POINT OF EXIT OF THE LEAD FROM THE BODY.
5. LEAD NUMBER 1 IDENTIFIED BY TAB ON LEAD OR DOT ON COVER.
6. DIMENSION "J" INCLUDES SOLDER LEAD FINISH.
7. LEAD NUMBERS SHOWN FOR REFERENCE ONLY.

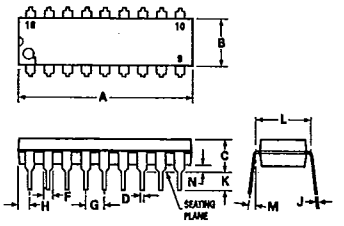
L SUFFIX
CERAMIC PACKAGE
CASE 693-02



DIM	MILLIMETERS MIN	MILLIMETERS MAX	INCHES MIN	INCHES MAX
A	9.91	10.92	0.390	0.430
B	6.22	6.99	0.245	0.275
C	4.32	5.08	0.170	0.200
D	0.41	0.51	0.016	0.020
F	1.40	1.65	0.055	0.065
G	2.54 BSC		0.100 BSC	
H	1.14	1.65	0.045	0.065
J	0.20	0.30	0.008	0.012
K	3.18	4.06	0.125	0.160
L	7.37	7.87	0.290	0.310
M	—	15°	—	15°
N	0.51	1.02	0.020	0.040

NOTES:
1. LEADS WITHIN 0.13 mm (0.005) RAD OF TRUE POSITION AT SEATING PLANE AT MAXIMUM MATERIAL CONDITION.
2. DIMENSION "L" TO CENTER OF LEADS WHEN FORMED PARALLEL.

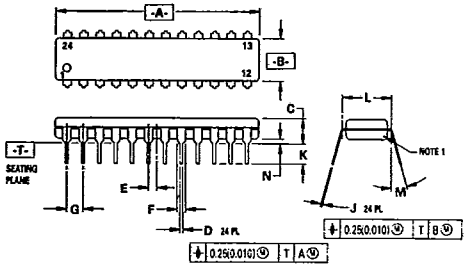
P SUFFIX
PLASTIC PACKAGE
CASE 707-02



DIM	MILLIMETERS MIN	MILLIMETERS MAX	INCHES MIN	INCHES MAX
A	22.22	23.24	0.875	0.915
B	6.10	6.60	0.240	0.260
C	3.56	4.57	0.140	0.180
D	0.36	0.56	0.014	0.022
F	1.27	1.78	0.050	0.070
G	2.54 BSC		0.100 BSC	
H	1.02	1.52	0.040	0.060
J	0.20	0.30	0.008	0.012
K	2.92	3.43	0.115	0.135
L	7.62 BSC		0.300 BSC	
M	0°	15°	0°	15°
N	0.51	1.02	0.020	0.040

NOTES:
1. POSITIONAL TOLERANCE OF LEADS (D), SHALL BE WITHIN 0.25mm(0.010) AT MAXIMUM MATERIAL CONDITION, IN RELATION TO SEATING PLANE AND EACH OTHER.
2. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
3. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

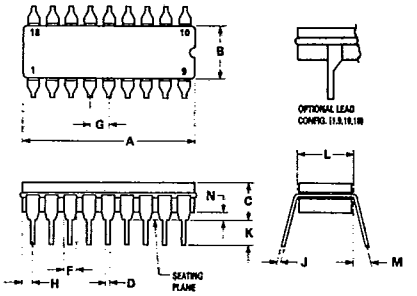
P SUFFIX
PLASTIC PACKAGE
CASE 724-03



DIM	MILLIMETERS MIN	MILLIMETERS MAX	INCHES MIN	INCHES MAX
A	31.25	32.13	1.230	1.265
B	6.35	6.85	0.250	0.270
C	3.69	4.44	0.145	0.175
D	0.38	0.51	0.015	0.020
E	1.27 BSC		0.050 BSC	
F	1.02	1.52	0.040	0.060
G	2.54 BSC		0.100 BSC	
J	0.18	0.30	0.007	0.012
K	2.80	3.55	0.110	0.140
L	7.62 BSC		0.300 BSC	
M	0°	15°	0°	15°
N	0.51	1.01	0.020	0.040

NOTES:
1. CHAMFERRED CONTOUR OPTIONAL.
2. DIM "L" TO CENTER OF LEADS WHEN FORMED PARALLEL.
3. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.
4. CONTROLLING DIMENSION: INCH.

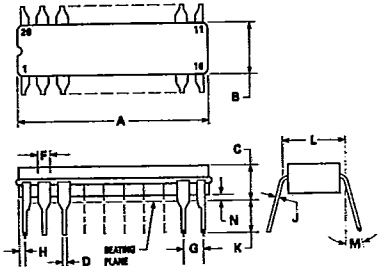
L SUFFIX
CERAMIC PACKAGE
CASE 726-04



DIM	MILLIMETERS MIN	MILLIMETERS MAX	INCHES MIN	INCHES MAX
A	22.35	23.11	0.880	0.910
B	6.10	7.49	0.240	0.295
C	—	5.08	—	0.200
D	0.38	0.53	0.015	0.021
F	1.40	1.78	0.055	0.070
G	2.54 BSC		0.100 BSC	
H	0.51	1.14	0.020	0.045
J	0.20	0.30	0.008	0.012
K	3.18	4.32	0.125	0.170
L	7.62 BSC		0.300 BSC	
M	0°	15°	0°	15°
N	0.51	1.02	0.020	0.040

NOTES:
1. LEADS, TRUE POSITIONED WITHIN 0.25 mm (0.010) DIA. AT SEATING PLANE, AT MAXIMUM MATERIAL CONDITION.
2. DIM "L" TO CENTER OF LEADS WHEN FORMED PARALLEL.
3. DIM "A" & "B" INCLUDES MENISCUS.
4. "F" DIMENSION IS FOR FULL LEADS. "HALF" LEADS ARE OPTIONAL AT LEAD POSITIONS 1, 9, 10, AND 18.

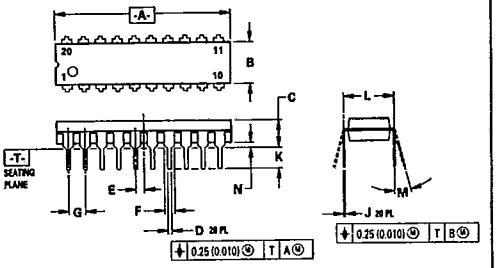
L SUFFIX
CERAMIC PACKAGE
CASE 732-03



DIM	MILLIMETERS MIN	MILLIMETERS MAX	INCHES MIN	INCHES MAX
A	23.88	25.15	0.940	0.990
B	6.60	7.49	0.260	0.295
C	3.81	5.08	0.150	0.200
D	0.38	0.56	0.015	0.022
F	1.40	1.65	0.055	0.065
G	2.54 BSC		0.100 BSC	
H	0.51	1.27	0.020	0.050
J	0.20	0.30	0.008	0.012
K	3.18	4.06	0.125	0.160
L	7.62 BSC		0.300 BSC	
M	0°	15°	0°	15°
N	0.25	1.02	0.010	0.040

NOTES:
1. LEADS WITHIN 0.25 mm (0.010) DIA., TRUE POSITION AT SEATING PLANE, AT MAXIMUM MATERIAL CONDITION.
2. DIM L TO CENTER OF LEADS WHEN FORMED PARALLEL.
3. DIM A AND B INCLUDES MENISCUS.

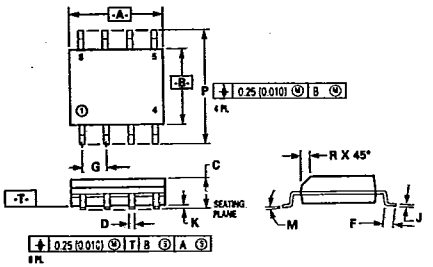
P SUFFIX
PLASTIC PACKAGE
CASE 738-03



DIM	MILLIMETERS MIN	MILLIMETERS MAX	INCHES MIN	INCHES MAX
A	25.66	27.17	1.010	1.070
B	6.10	6.60	0.240	0.260
C	3.81	4.57	0.150	0.180
D	0.39	0.55	0.015	0.022
E	1.27 BSC		0.050 BSC	
F	1.27	1.77	0.050	0.070
G	2.54 BSC		0.100 BSC	
J	0.21	0.38	0.008	0.015
K	2.80	3.55	0.110	0.140
L	7.62 BSC		0.300 BSC	
M	0°	15°	0°	15°
N	0.51	1.01	0.020	0.040

NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION "L" TO CENTER OF LEAD WHEN FORMED PARALLEL.
4. DIMENSION "B" DOES NOT INCLUDE MOLD FLASH.

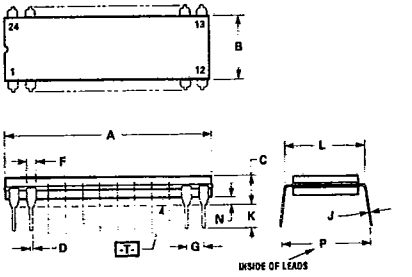
D SUFFIX
PLASTIC SOIC PACKAGE
CASE 751-03



DIM	MILLIMETERS MIN	MILLIMETERS MAX	INCHES MIN	INCHES MAX
A	4.80	5.00	0.189	0.196
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.18	0.25	0.007	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.228	0.244
R	0.25	0.50	0.010	0.019

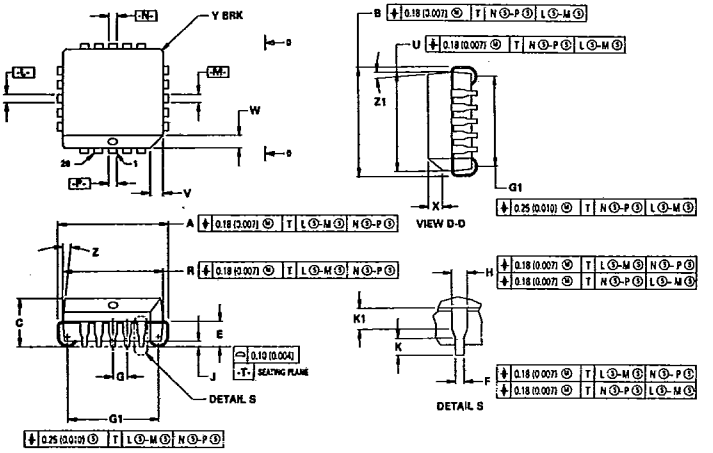
NOTES:
1. DIMENSIONS "A" AND "B" ARE DATUMS AND "T" IS A DATUM SURFACE.
2. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
3. CONTROLLING DIM: MILLIMETER.
4. DIMENSION "A" AND "B" DO NOT INCLUDE MOLD PROTRUSION.
5. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.

L SUFFIX
CERAMIC PACKAGE
CASE 758-01



DIM	MILLIMETERS MIN	MILLIMETERS MAX	INCHES MIN	INCHES MAX
A	31.50	32.64	1.240	1.285
B	7.24	7.75	0.285	0.305
C	3.68	4.44	0.145	0.175
D	0.38	0.53	0.015	0.021
F	1.14	1.57	0.045	0.062
G	2.54 BSC		0.100 BSC	
J	0.20	0.33	0.008	0.013
K	2.54	4.19	0.100	0.165
L	7.62	7.87	0.300	0.310
N	0.51	1.27	0.020	0.050
P	9.14	10.16	0.360	0.400

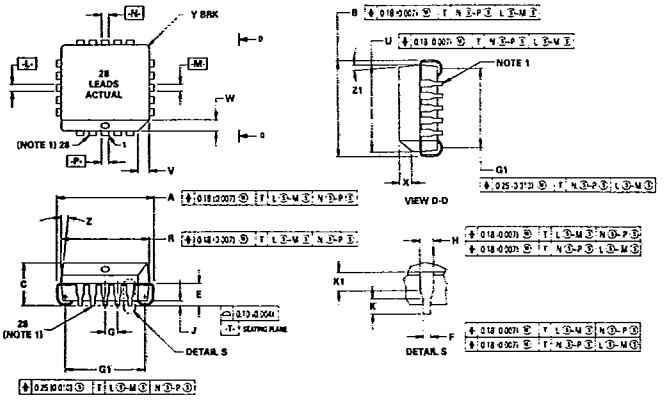
NOTES:
1. DIMENSION A IS DATUM.
2. POSITIONAL TOLERANCE FOR LEADS: 24 PLACES
   0.25 (0.010) S T A S
3. -T- IS SEATING PLANE.
4. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
5. DIMENSIONING AND TOLERANCING PER ANSI Y14.5, 1973.



NOTES:
1. DATUMS -L-, -M-, -N-, AND -P- DETERMINED WHERE TOP OF LEAD SHOULDER EXIT PLASTIC BODY AT MOLD PARTING LINE.
2. DIM G1, TRUE POSTION TO BE MEASURED AT DATUM -T-, SEATING PLANE.
3. DIM R AND U DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.25 (0.010) PER SIDE.
4. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
5. CONTROLLING DIMENSION: INCH.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	9.78	10.03	0.385	0.395
B	9.78	10.03	0.385	0.395
C	4.20	4.57	0.165	0.180
E	2.29	2.79	0.090	0.110
F	0.33	0.48	0.013	0.019
G	1.27 BSC		0.050 BSC	
H	0.66	0.81	0.026	0.032
J	0.51	—	0.020	—
K	0.64	—	0.025	—
R	8.89	9.04	0.350	0.356
U	8.89	9.04	0.350	0.356
V	1.07	1.21	0.042	0.048
W	1.07	1.21	0.042	0.048
X	1.07	1.42	0.042	0.056
Y	—	0.50	—	0.020
Z	2°	10°	2°	10°
G1	7.88	8.38	0.310	0.330
K1	1.02	—	0.040	—
Z1	2°	10°	2°	10°

FN SUFFIX
PLASTIC PACKAGE
CASE 775-02



NOTES:
1. **DUE TO SPACE LIMITATION, CASE 776-02 SHALL BE REPRESENTED BY A GENERAL (SMALLER) CASE OUTLINE DRAWING RATHER THAN SHOWING ALL 28 LEADS.**
2. DATUMS -L-, -M-, -N-, AND -P- DETERMINED WHERE TOP OF LEAD SHOULDER EXIT PLASTIC BODY AT MOLD PARTING LINE.
3. DIM G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.
4. DIM R AND U DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.25 (0.010) PER SIDE.
5. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
6. CONTROLLING DIMENSION: INCH.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	12.32	12.57	0.485	0.495
B	12.32	12.57	0.485	0.495
C	4.20	4.57	0.165	0.180
E	2.29	2.79	0.090	0.110
F	0.33	0.48	0.013	0.019
G	1.27 BSC		0.050 BSC	
H	0.66	0.81	0.026	0.032
J	0.51	—	0.020	—
K	0.64	—	0.025	—
R	11.43	11.58	0.450	0.456
U	11.43	11.58	0.450	0.456
V	1.07	1.21	0.042	0.048
W	1.07	1.21	0.042	0.048
X	1.07	1.42	0.042	0.056
Y	—	0.50	—	0.020
Z	2°	10°	2°	10°
G1	10.42	10.92	0.410	0.430
K1	1.02	—	0.040	—
Z1	2°	10°	2°	10°

FN SUFFIX
PLASTIC PACKAGE
CASE 776-02

offer answers to many problems that have been created in the use of insertion technology.

Limitations have been reached with insertion packages and PC board technology. Surface Mount Technology offers the opportunity to continue to advance the State-of-the-Art designs that cannot be accomplished with Insertion Technology.

Surface Mount Packages allow more optimum device performance with the smaller Surface Mount configuration. Internal lead lengths, parasitic capacitance and inductance that placed limitations on chip performance have been reduced.

The lower profile of Surface Mount Packages allows more boards to be utilized in a given amount of space. They are stacked closer together and utilize less total volume than insertion populated PC boards.

Printed circuit costs are lowered with the reduction of the number of board layers required. The elimination or reduction of the number of plated through holes in the board, contribute significantly to lower PC board prices.

Surface Mount assembly does not require the preparation of components that are common on insertion technology lines. Surface Mount components are sent directly to the assembly line, eliminating an intermediate step.

Automatic placement equipment is available that can place Surface Mount components at the rate of a few thousand per hour to hundreds of thousands of components per hour.

Surface Mount Technology is cost effective, allowing the manufacturer the opportunity to produce smaller units and offer increased functions with the same size product.

MECL AVAILABILITY IN SURFACE MOUNT

Motorola is now offering MECL 10K and MECL 10KH in the PLCC (Plastic Leaded Chip Carrier) packages.

MECL in PLCC may be ordered in conventional plastic rails or on Tape and Reel. Refer to the Tape and Reel section for ordering details.

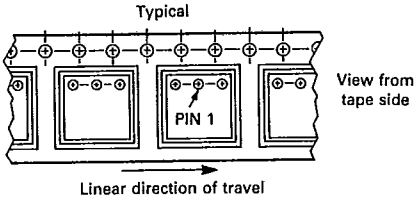
TAPE AND REEL

Motorola has now added the convenience of Tape and Reel packaging for our growing family of standard Integrated Circuit products. The packaging fully conforms to embossed tape provides a secure cavity sealed with a peel-back cover tape.

GENERAL INFORMATION

- Reel Size 13 inch (330 mm) Suffix: R2
- Tape Width 16 mm
- Units/Reel 1000

MECHANICAL POLARIZATION



ORDERING INFORMATION

- Minimum Lot Size/Device Type = 3000 Pieces.
- No Partial Reel Counts Available.
- To order devices which are to be delivered in Tape and Reel, add the appropriate suffix to the device number being ordered.

EXAMPLE:

ORDERING CODE	SHIPMENT METHOD
MC10100FN	Magazines (Rails)
MC10100FNR2	13 inch Tape and Reel
MC10H100FN	Magazines (Rails)
MC10H100FNR2	13 inch Tape and Reel
MC12015D	Magazines (Rails)
MC12015DR2	13 inch Tape and Reel

DUAL-IN-LINE PACKAGE TO PLCC PIN CONVERSION DATA

The following tables give the equivalent I/O pinouts of Dual-In-Line (DIL) packages and Plastic Leaded Chip Carrier (PLCC) packages.

Conversion Tables

16 PIN DIL	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16
20 PIN PLCC	2	3	4	5	7	8	9	10	12	13	14	15	17	18	19	20

20 PIN DIL	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20
20 PIN PLCC	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20

24 PIN DIL	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21	22	23	24
28 PIN PLCC	2	3	4	5	6	7	9	10	11	12	13	14	16	17	18	19	20	21	23	24	25	26	27	28